

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS**

166. (Currently Amended) A surface acoustic wave device, comprising:

    a printed circuit board including a first board surface and a second board surface, the first board surface having a board wiring pattern, a part of the board wiring pattern, that is a board wiring pad, being thicker in thickness of conductive material than that of the other part;

    a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a an element wiring pad, and a surface acoustic wave absorbing member formed outside of the element wiring pad, and the first element surface being disposed in an opposite relation with respect to the first board surface;

    a conductive connecting member disposed between the board wiring pad and the element wiring pad; and

    a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

167. (Previously Amended) The surface acoustic wave device as set forth in Claim 166, wherein a difference between the first thickness and the second thickness is in the range of from 5  $\mu$ m to 100  $\mu$ m.

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168. (Currently Amended) A surface acoustic wave device, comprising:

a printed circuit board of a material possessing a first region and a second region which is thicker than the first region, the second region including a board wiring pad thereon;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a an element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board;

a conductive connecting member disposed between the board wiring pad and the element wiring pad; and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

169. (Previously Amended) The surface acoustic wave device as set forth in claim 168, wherein a difference between a thickness of the first region and that of the second region of the printed circuit board material is in the range of from 5  $\mu\text{m}$  to 500  $\mu\text{m}$ .

170. (Currently Amended) A surface acoustic wave device, comprising:

a printed circuit board including a first board surface and a second board surface, the first board surface having a board wiring pattern;

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a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a an element wiring pad and a surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad; and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

171. (Previously Added) The surface acoustic wave device as set forth in Claim 170, wherein a thickness of the conductive connecting member is larger than a thickness of the surface acoustic wave absorbing member.

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